

10-10-2001

Docket No.: 501.40695X00

SHEET

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

101869851

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Masakatsu GOTOU, Norihiko KASAI

2. Name and address of receiving party(ies):

Name: 1. Hitachi, Ltd.

2. Hitachi Hokkai Semiconductor, Ltd.

Street Address: 1. 6, Kanda Surugadai 4-chome, Chiyoda-ku

2. 145, Azanakajima, Nanaecho, Kameda-gun

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other _____

Execution Date: August 29, 2001

City: 1. Tokyo

2. Hokkaido

Country: Japan

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: August 29, 2001

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: ANTONELLI, TERRY, STOUT & KRAUS, LLP

Internal Address:

Street Address: 1300 North Seventeenth Street
Suite 1800

City: Arlington State: VA Zip: 22209

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$40.00

☒ Enclosed☒ Any deficiencies may be charged to deposit account☐ Authorized to be charged to deposit account

8. Deposit account number: 01-2135

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*William I. Solomon

Name of Person Signing

Attorney Registration No. 28,565

Signature

September 28, 2001

Date

Total number of pages including cover sheet, attachments, and document: 2

OMB No. 0651-0011 (exp. 4/94)

10/02/2001 AB00NE1 00000014 09965221

04 FC:581

40.00 OF

PATENT
REEL: 012221 FRAME: 0872

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD. and Hitachi Hokkai Semiconductor, Ltd., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, and 145, Azanakajima, Nanaecho, Kameda-gun, Hokkaido, Japan, respectively, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD. and Hitachi Hokkai Semiconductor, Ltd., their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

A METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner ship of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD. and Hitachi Hokkai Semiconductor, Ltd., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD. and Hitachi Hokkai Semiconductor, Ltd.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1) Masakatsu GOTOU (Masakatsu GOTOU)

2) Norihiko KASAI (Norihiko KASAI)

3) _____

4) _____

5) _____

6) _____

7) _____

8) _____

9) _____

10) _____

29 / August / 2001

29 / August / 2001
~~6 / September / 2001~~ N.K.
